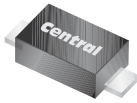
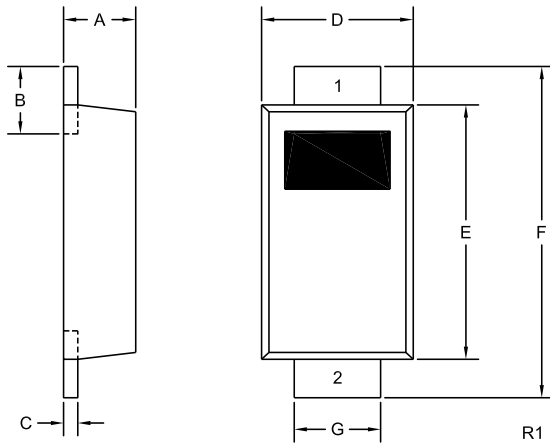


**Package Details**  
SOD-123F Case



**Mechanical Drawing**



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.035	0.043	0.88	1.08
B	0.020	0.031	0.50	0.80
C	0.004	0.008	0.10	0.20
D	0.065	0.077	1.65	1.95
E	0.104	0.116	2.65	2.95
F	0.140	0.156	3.55	3.95
G	0.030	0.041	0.75	1.05

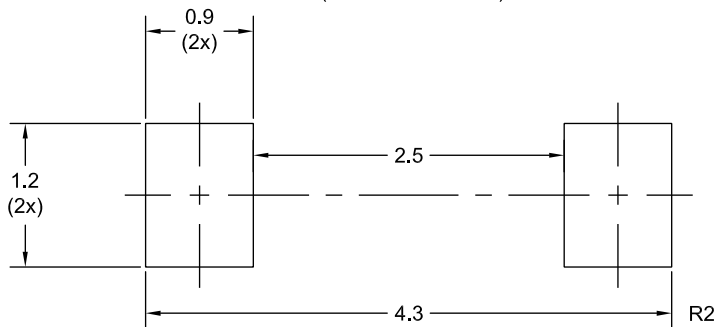
SOD-123F (REV:R1)

**Lead Code:**

- 1) Cathode
- 2) Anode

**Part Marking:** 3 Character Alpha/Numeric Code

**Mounting Pad Geometry (Dimensions in mm)**



R1 (4-March 2010)

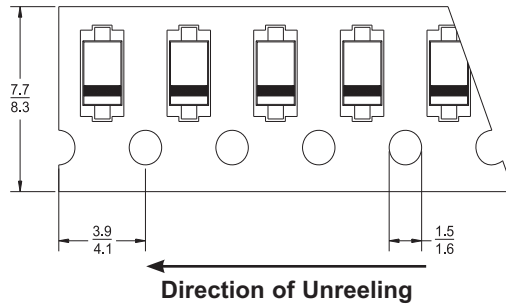
# Package Details

## SOD-123F Case



### Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



\* Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

### Packaging Base

7" Reel = 3,000 pcs.

### Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

### Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7"	8	24,000	9x9x5	23x23x13	4	2
	17	51,000	9x9x9	23x23x23	8	4
	40	120,000	21x9x9	53x23x23	17	8
	108	324,000	27x9x17	69x23x43	45	21

### Ordering Information

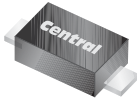
- For devices taped and reeled on 7" reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

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# Material Composition Specification

SOD-123F Case

Pb (lead)-free plating\*\*



Device average mass ..... 17.0 mg

Fluctuation margin ..... +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	4.59%	0.78	Si	7440-21-3	4.59%	0.78	45,882
leadframe	Cu alloy	49.47%	8.41	Cu	7440-50-8	47.06%	8.0	470,588
				Fe	7439-89-6	2.41%	0.41	24,118
die attach	high temperature solder paste	7.65%	1.30	Pb	7439-92-1	7.08%	1.203	70,765
				Sn	7440-31-5	0.38%	0.065	3,824
				Ag	7440-22-4	0.19%	0.032	1,882
encapsulation*	EMC	37.94%	6.45	silica	7631-86-9	26.24%	4.461	262,412
				epoxy resin	Proprietary	11.24%	1.911	112,412
				Sb <sub>2</sub> O <sub>3</sub>	1309-64-4	0.04%	0.007	412
				Br	7726-95-6	0.42%	0.071	4,176
	EMC GREEN	37.94%	6.45	silica (fused)	60676-86-0	29.22%	4.967	292,176
				epoxy resin	29690-82-2	3.79%	0.645	37,941
				phenol resin	9003-35-4	3.68%	0.626	36,824
				carbon black	1333-86-4	0.11%	0.019	1,118
	metal hydroxide	1309-42-8	1.14%	0.193	11,353			
plating**	tin lead process	0.35%	0.06	Sn	7440-31-5	0.29%	0.05	2,941
				Pb	7439-92-1	0.06%	0.01	588
	100% matte tin	0.35%	0.06	Sn	7440-31-5	0.35%	0.06	3,529

\*EMC GREEN molding compound is Halogen-Free.

\*\*Specify Lead-Free when ordering 100% tin (Pb-free) plating.

**Disclaimer**

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (9-March 2010)